APPENDIX D

(VERSION OF CLAIMS AS AMENDED HEREIN WITH MARKINGS TO SHOW CHANGES MADE)

(Serial No. 09/888,689)

VERSION OF CLAIMS WITH MARKINGS TO SHOW CHANGES MADE

1. (Amended) A method of forming a probe card comprising:

providing a substrate having a first surface and a second surface;

disposing a plurality of conductive traces adjacent at least one of the first surface and the second surface;

providing a plurality of probe elements in electrical communication with the plurality of conductive traces; and

providing a plurality of fuse elements in respective electrical communication with at least some of the plurality of conductive traces, at least some of the plurality of fuse elements disposed immediately adjacent the at least one of the first surface and the second surface.

3. (Amended) The method of claim 1, wherein said providing a plurality of fuse elements comprises providing at least one fuse element of the plurality of fuse elements configured to be replaceable or repairable after being tripped.

7. (Amended) The method of claim 3, further comprising providing a plurality of test contacts adjacent the at least one of the first surface and the second surface of the substrate, at least some of the plurality of test contacts in electrical communication with respective conductive traces of the plurality of conductive traces, and further comprising forming each of the plurality of conductive traces, the plurality of fuse elements, and the plurality of test contacts of the same materials.

8. (Amended) The method of claim 1, wherein said providing a plurality of fuse elements comprises inserting at least one of the plurality of fuse elements in through-hole portions configured in the at least one of the first surface and the second surface of the substrate.

11. (Amended) The method of claim 1, wherein at least one fuse element of the plurality of fuse elements is configured to be self-resetting after being tripped.

12. (Amended) The method of claim 11, wherein the at least one fuse element is configured as a PPTC fuse.

13. (Amended) The method of claim 11, wherein the at least one fuse element is configured as a bimetallic switch.

16. (Amended) The method of claim 14, wherein said providing a plurality of probe elements comprises providing [the]a plurality of probe elements in a configuration adapted to be temporarily electrically coupled with a semiconductor wafer having a plurality of electrical contacts thereon.

18. (Amended) The method of claim 16, wherein said providing a probe card substrate includes providing [the]a probe card substrate with a coefficient of thermal expansion which substantially matches a coefficient of thermal expansion of the semiconductor wafer.

22. (Amended) A method of using a probe card for testing at least one semiconductor die, comprising:

providing a probe card having a plurality of probe elements connected thereto, the plurality of probe elements configured for supplying test signals to the at least one semiconductor die;

providing a plurality of fuses in electrical communication with at least some of the plurality of probe elements; and

testing the at least one semiconductor die by supplying test signals to the at least one semiconductor die through [the]a fuse of the plurality of fuses.

29. (Amended) The probe card of claim 26, wherein at least one of the plurality of fuses and at least one of the plurality of conductive traces are constructed of the same materials.

30. (Amended) The probe card of claim 26, wherein at least one of the plurality of fuses and at least one of the plurality of conductive traces are constructed over a surface of the probe card during a single deposition process.

48. (Amended) The probe card of claim 26, wherein the plurality of probe elements [are]is configured in a pattern for simultaneously testing integrated circuitry of a plurality of semiconductor dice.